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P. Williams

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Date of Deposit

Tadashi Horie

Name of applicant, assignee or
Registered Representative

Tadashi Horie

Signature

November 5, 2001

Date of Signature

Our Case No. 10269/3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

TAKUMI MIZOKAWA et al.

Serial No. 09/490,507

Filing Date: January 25, 2000

For CONVEYANCE SYSTEM

Examiner: Bratlie, S.

Group Art Unit No.: 3652

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

RECEIVED
DEC 03 2001

GROUP 3600

Dear Sir:

In response the Office Action mailed July 9, 2001, please enter the following amendment and consider the following remarks:

IN THE CLAIMS:

- (1) Please replace claim 1 with the following new claim 1 (APPENDIX 1):

1. (once amended) A wafer conveyance system, comprising:
a plurality of wafer processing apparatuses each having an insertion portion;
a guide path defined along said plurality of wafer processing apparatuses;

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